



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20191118001.1A

**Qualification of CDAT as an additional assembly site for select QFN devices
Change Notification / Sample Request**

Date: January 31, 2020

Dear TI Customer:

Revision A is to announce the addition of new devices that were not included on the original PCN notification.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

The customer should acknowledge receipt of this notification by email within **30** days of the date of receipt. Lack of acknowledgement of this notice within 30 days constitutes customer acceptance of the change.

Samples or additional data to support customer evaluation must be requested within 30 days of receipt of this notification. If samples are requested for evaluation the customer must provide evaluation results within the sample evaluation period indicated on page 3 of this notification. The Sample Evaluation Period begins on the date the customer receives samples from TI.

If the customer approved the change TI can proceed with implementation of the change. The proposed first ship date is shown on page 3.

If the customer does not approve the PCN or the approval response is not provided within the Sample Evaluation Period, TI can implement the change, but the customer may elect to place an order for unchanged product by the Last Time Buy Date for delivery by the Last Time Ship Date. TI cannot guarantee that shipments to the customer after any last time order is delivered will not include the changed material. If the customer places an order with delivery after the Last Time Shipment Date, the order may be fulfilled with changed material or any material processed to TI specifications at that future time.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team
SC Business Services

20191118001.1A
Change Notification / Sample Request
Attachments




Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ24780SRUYR	39070396

Technical details of this Product Change follow on the next page(s).

PCN Number:	20191118001.1A		PCN Date:	Jan 31, 2020																					
Title:	Qualification of CDAT as an additional assembly site for select QFN devices																								
Customer Contact:	PCN Manager	Dept:	Quality Services																						
Proposed 1st Ship Date:	Feb 20, 2020	Sample Eval Period:	90 days																						
Last Time Buy Date:	Jun 29, 2020	Last Time Ship Date:	Sept 27, 2020																						
Change Type:																									
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>																					
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>																					
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>																					
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>																					
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>																					
				<input type="checkbox"/>																					
				Wafer Bump Site																					
				Wafer Bump Material																					
				Wafer Bump Process																					
				Wafer Fab Site																					
				Wafer Fab Materials																					
				Wafer Fab Process																					
PCN Details																									
Description of Change:																									
<p>Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification. These new devices are under Group 2 in the product affected section below. The expected first shipment date for these new devices will be 90 days from this notice (Apr 31, 2020 for Rev A) for these newly added devices only. The proposed 1st ship date of Feb 20, 2020 still applies for the original set of devices.</p> <p>Texas Instruments is pleased to announce the qualification of CDAT as an additional assembly site for the list of QFN devices shown below. Current assembly sites and Material differences are as follows:</p> <p>Group 1 device:</p> <table border="1"> <thead> <tr> <th></th> <th>UTAC</th> <th>Clark</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>SID#CZ0289</td> <td>4208625</td> <td>4222198</td> </tr> <tr> <td>Mount Compound</td> <td>SID#PZ0035</td> <td>4207123</td> <td>4207123</td> </tr> </tbody> </table> <p>Group 2 device:</p> <table border="1"> <thead> <tr> <th></th> <th>Clark</th> <th>CDAT</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>4208625</td> <td>4222198</td> </tr> <tr> <td>Mount Compound</td> <td>4207768</td> <td>4207123</td> </tr> </tbody> </table>						UTAC	Clark	CDAT	Mold Compound	SID#CZ0289	4208625	4222198	Mount Compound	SID#PZ0035	4207123	4207123		Clark	CDAT	Mold Compound	4208625	4222198	Mount Compound	4207768	4207123
	UTAC	Clark	CDAT																						
Mold Compound	SID#CZ0289	4208625	4222198																						
Mount Compound	SID#PZ0035	4207123	4207123																						
	Clark	CDAT																							
Mold Compound	4208625	4222198																							
Mount Compound	4207768	4207123																							
Reason for Change:																									
Continuity of Supply																									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																									
None																									
Anticipated impact on Material Declaration																									
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp																						
Changes to product identification resulting from this PCN:																									
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City																						
CLARK	QAB	PHL	Angeles City, Pampanga																						

CDAT	CDA	CHN	Chengdu
Sample product shipping label (not actual product label)			
<div>    <div> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS </div> </div> <div> MADE IN: Malaysia 2DC: 2Q: MSL '2 / 260C/1 YEAR SEAL DT MSL 1 / 235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 </div>			
Product Affected: Group 1			
CC1312R1F3RGZR	CC1352P1F3RGZT	CC2642R1FRGZR	CC2652R1FRGZT
CC1312R1F3RGZT	CC1352R1F3RGZR	CC2642R1FRGZT	
CC1352P1F3RGZR	CC1352R1F3RGZT	CC2652R1FRGZR	
Product Affected: Group 2			
BQ24780SRUYR	SN2850RUYR	SN2867RUYR	
BQ24780SRUYT	SN2850RUYT	SN2867RUYT	

Group 1: Qualification Report

Approve Date 08-Nov-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC1352P1F3RGZR	QBS Package Reference: CC2640R2FRGZR	QBS Package Reference: CC2640R2FRSMR
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	3/231/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	1/77/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	3/78/0	-

- QBS: Qual By Similarity
 - Qual Device CC1352P1F3RGZR is qualified at LEVEL3-260C
 - Preconditioning was performed for Autoclave, THB, Temperature Cycle, and HTSL.
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Group 2: Qualification Report

Approve Date 16-Jan-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>BQ24780SRUY</u>	QBS Product Reference: <u>BQ24780SRUY</u>	QBS Product Reference: <u>TLS2602DCA</u> (CARDINAL)	QBS Package Reference: <u>TPS51220ARSNR</u>	QBS Package Reference: <u>TPS53641RSBR</u>
AC	Autoclave 121C	192 Hours	-	-	-	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	-	-	-
HBM	ESD - HBM	2000 V	-	1/3/0	3/81/0	-	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	3/231/0	-	-
LU	Latch-up	(per JESD78)	-	1/6/0	3/18/0	-	-
PD	Physical Dimensions	--	1/5/0	-	-	3/15/0	3/15/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	1/77/0	-	3/231/0

- QBS: Qual By Similarity
 - Qual Device BQ24780SRUY is qualified at LEVEL2-260CG
 - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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